Notification# 20191103003
Datasheet for HDC2010
Information Only

Date: November 06, 2019
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
HDC2010YPAT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20191103003	PCN Date:	Nov. 6, 2019
Title:	Datasheet for HDC2010		
Customer Contact:	PCN Manager	**Dept:**	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

TEXAS INSTRUMENTS

Changes from Revision B (August 2018) to Revision C   **Page**

- Added pin type description for DRDY/INT pin 3
- Changed description of behavior of TH_STATUS bit when INT_MODE is set to 1 11
- Changed description of behavior of TH_STATUS bit when INT_MODE is set to 0 11
- Changed description of behavior of TL_STATUS bit when INT_MODE is set to 1 12
- Changed description of behavior of TL_STATUS bit when INT_MODE is set to 0 12
- Changed description of behavior of HH_STATUS bit when INT_MODE is set to 1 13
- Changed description of behavior of HH_STATUS bit when INT_MODE is set to 0 13
- Changed description of behavior of HL_STATUS bit when INT_MODE is set to 1 14
- Changed description of behavior of HL_STATUS bit when INT_MODE is set to 0 14
- Changed the units for Humidity threshold low from: °C to: %RH 24
- Changed the temperature resolution decoding from: 8 bit to: 9 bit 26
- Changed the humidity resolution decoding from: 8 bit to: 9 bit 26
- Changed the measurement configuration "10" bit encoding from: Humidity Only to: NA for field MEAS_CONFIG[1:0] 26

The datasheet number will be changing.

Device Family	Change From:	Change To:
HDC2010	SNAS693B	SNAS693C

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/HDC2010

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

HDC2010YPAR	HDC2010YPAT		

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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